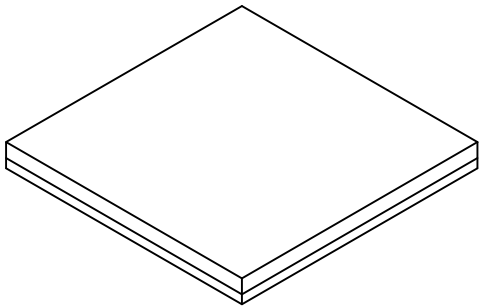
REVISION HISTORY					
REV	DCN NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR	DATE
00	C8375	INITIAL RELEASE	SDEFO	SDEFO	03/16/00
01	A54961	ADDED 288 FOOTPRINT IN SHEET 3	MCSHIN	MCSHIN	05/14/02
02	N/A	ADDED 260 FOOTPRINT IN SHEET 3	HJKHIM	HJKHIM	07/22/05



7. REFERENCE SPECIFICATIONS:
   A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
   B. AAWW SPEC #001-0519-2062: MARKING.

6 PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5 DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 484.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 22 X 22.

2. THE BASIC SOLDER BALL GRID PITCH IS 0.50.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
DECIMAL: X.X ±0.1, X.XX ±0.05, X.XXX ±0.030
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994
MATERIAL: N/A
FINISH: N/A
DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION

APPROVALS	DATE
DESIGNED: SDEFO	02/29/00
CHECKED: HLE	02/29/00
PRODUCT MANAGER: DARNO	02/29/00
RELEASED: GSCHU	03/16/00

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

TITLE: PACKAGE OUTLINE, CTBGA ,
12.00mm X 12.00mm, 0.60 CAP, 2 LAYER,
0.50mm PITCH, LAMINATE SUBSTRATE, AAWW

SIZE	SID NUMBER	DWG NUMBER	REV
A3	N/A	79089	02

STRIP DWG NUMBER/REV	PKG OUTLINE DWG NO.	SCALE	SHEET
N/A	N/A	NONE	1 OF 4

FORM NO: MBFLA41C1.DWG